

# **DATA SHEET**

**GENERAL PURPOSE CHIP RESISTORS** 

**RC0805** 

5%, 1%, 0.5%, 0.1% RoHS Compliant & Halogen Free



YAGEO Phicomp





Chip Resistor Surface Mount RC SERIES 0805 5

#### **SCOPE**

This specification describes RC0805 series chip resistors with lead-free terminal made by thick film process.

#### ORDERING INFORMATION

Part number is identified by the series, size, tolerance, packing style, temperature coefficient, taping reel, resistance value.

RC0805  $\underline{X}$   $\underline{R}$   $\underline{-}$   $\underline{XX}$   $\underline{XXX}$   $\underline{L}$ 

(1) (2) (3) (4) (5) (6)

**MARKING** 

RC0805

(1) TOLERANCE

 $B = \pm 0.1\%$ 

 $F = \pm 0.5\%$  $F = \pm 1\%$ 

 $J = \pm 5\%$  ( for jumper ordering use code of J)

(2) PACKAGING TYPE

R = Paper taping reel

103

Fig.1 Value =  $10k\Omega$ 

5% E-24 series: 3 digits

First two digits for significant figure and 3rd digit for number of zeros.

# (3) TEMPERATURE COEFFICIENT OF RESISTANCE

— = base on spec.

(4) TAPING REEL

07 = 7 inch dia. Reel

1002

Fig.2 Value =  $10K\Omega$ 

Both 1% E-24 and E-96 series: 4 digits First three digits for significant figure and 4th digit for number of zeros.

#### (5) RESISTANCE VALUE

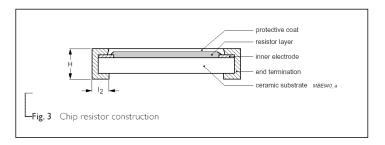
 $1\Omega$  to  $100M\Omega$ 

#### (6) Default Code

Letter L is system default code for order only (NOTE)

#### **CONSTRUCTION**

The resistors are constructed out of a high-grade ceramic body. Internal metal electrodes are added at each end and connected by a resistive material. The composition of the resistive material is adjusted to give the approximate required resistance and laser cutting of this resistive layer that achieves tolerance trims the value. The resistive layer is covered with a protective coat and printed with the resistance value. Finally, the two external terminations are added. See fig.3



Note

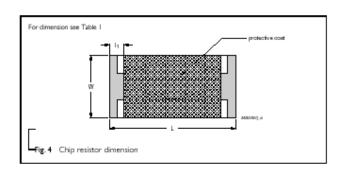
1. All our RSMD products meet RoHS compliant and Halogen Free. "LFP" of the internal 2D reel label mentions "Lead Free Process".

2. On customized label, "LFP" or specific symbol can be printed

**SERIES** 

#### **DIMENSION**

_Table 1	
TYPE	RC0805
L (mm)	2.00±0.10
W (mm)	1.25±0.10
H (mm)	0.50±0.10
I1 (mm)	0.35±0.20
I2 (mm)	0.35±0.20



### **POWER RATING**

RATED POWER AT 70°C,

#### RC0805 0.25W

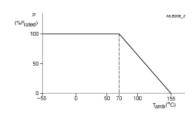


Fig. 5 Maximum dissipation (P) in percentage of rated power as a function of the operating ambient temperature (T<sub>amb</sub>)

# **ELECTRICAL CHARACTERISTICS**

I able 2	
CHARACTERISTICS	RC0805 0.25 W
Operating Temperature Range	–55°C to +155°C
Maximum Working Voltage	150V
Maximum Overload Voltage	300V
Dielectric Withstanding Voltage	300V
Resistance Range	$\pm$ 5% (E24) 1Ω to 100MΩ

 $\pm$ 1% ( E24/E96) 1Ω to 10MΩ

 $\pm 0.1\%$ , 0.5% ( E24/E96)  $10\Omega$  to  $1M\Omega$ 

	Ju	umper <50mΩ
Temperature Coefficient	1Ω≤ R ≤10Ω	±200ppm/°℃
	10Ω< R ≤10MΩ	±100ppm/°C
	10MΩ< R ≤22MΩ	±200ppm/°℃
	24MΩ< R ≤100MΩ	±300ppm/°℃
Jumper Criteria	Rated Currer	nt 2A
	Maximum Currer	nt 5A

#### **RATED VOLTAGE:**

The DC or AC (rms) continuous working voltage corresponding to the rated power is determined by the following formula:

$$V = \sqrt{(P * R)}$$

Where

V=Continuous rated DC

or AC (rms) working voltage

P=Rated power

R=Resistance value



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## **TAPING REEL**

 DIMENSION
 RC0805

 Tape Width(mm)
 8

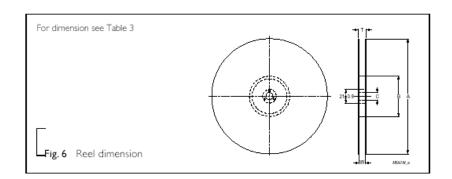
 ØA (mm)
 180+0/-3

 ØB (mm)
 60+1/-0

 ØC (mm)
 13.0±0.2

 W (mm)
 9.0±0.3

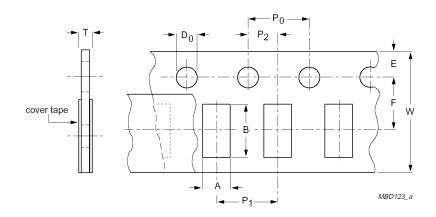
 T (mm)
 11.4±1



# **PAPER TAPE SPECIFICATION**

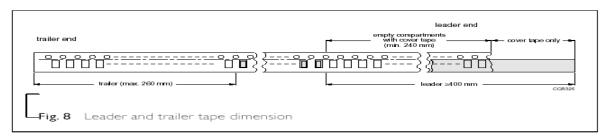
\_\_\_Table 4

DIMENSION	RC0805
A (mm)	1.9±0.1
B (mm)	3.5±0.1
W (mm)	8.0±0.2
E (mm)	1.75±0.1
F (mm)	3.5±0.05
P <sub>0</sub> (mm)	4.0±0.05
P <sub>1</sub> (mm)	4.0±0.1
P <sub>2</sub> (mm)	2.0±0.05
$ØD_0$ (mm)	1.5+0.1/-0
T (mm)	0.85±0.1



# **PACKING METHOD**

#### LEADER/TRAILER TAPE SPECIFICATION



\_Table 5 Packing style and packaging quantity.

PACKING STYLE	REEL DIMENSION	RC0805
Paper taping reel	7" (178 mm)	5,000

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# **TESTS AND REQUIREMENTS**

TEST	TEST METHOD	PROCEDURE	REQUIREMENT
Life/	MIL-STD 202 Method 108	At 70±2°C for 1,000 hours; RCWV applied	$\pm (1\% + 0.05 \Omega)$ for 0.1%/
Endurance	IEC 60115-1 4.25.1	for 1.5 hours on and 0.5 hour off, still air required	0.5%/ 1% tol.
			$\pm (3\% + 0.05 \Omega)$ for 5% tol.
			<100mΩ for jumper
High	MIL-STD 202 Method 108	1,000 hours at maximum operating	$\pm (1\% + 0.05 \Omega)$ for 0.1%/
Temperature Exposure	IEC 60068-2-2	temperature depending on specification, unpowered	0.5%/ 1% tol.
Lxposure			$\pm (2\% + 0.05 \Omega)$ for 5% tol.
			<50m $\Omega$ for jumper
Moisture	MIL-STD-202 Method 106	Each temperature / humidity cycle is	$\pm (0.5\% + 0.05\Omega)$ for 0.1%/
Resistance		defined at 8 hours (method 106), 3 cycles / 24 hours for 10d with 25 °C / 65 °C 95%	0.5%/ 1% tol.
		R.H, without steps 7a & 7b, unpowered	$\pm (2\% + 0.05 \Omega)$ for 5% tol.
		Parts mounted on test-boards, without condensation on parts	<100m $\Omega$ for jumper
Thermal	MIL-STD-202 Method 107	-55/+125℃	$\pm (0.5\% + 0.05\Omega)$ for 0.1%/
Shock		Note Number of cycles required is 300 Devices mounted	0.5%/ 1% tol.
		Maximum transfer time is 20 seconds	$\pm$ (1%+0.05 $\Omega$ ) for 5% tol.
		Dwell time is 15 minutes. Air - Air	<50m $\Omega$ for jumper
Short Time	IEC 60115-1 4.13	2.5 times RCWV or maximum overload voltage which is less for 5 seconds at room temperature	$\pm (1\% + 0.05 \Omega)$ for 0.1%/
Overload			0.5%/ 1% tol.
			$\pm (2\% + 0.05 \Omega)$ for 5% tol.
			$<$ 50m $\Omega$ for jumper
	U=0 0044= 4 4 00		No visible damage
Board Flex/	IEC 60115-1 4.33	Device mounted or as described only 1 board bending required	±(1%+0.05Ω)
Bending		3 mm bending time: 60±5 seconds	<50m Ω for jumper
		5 5	No visible damage
Solderability	J-STD-002 test B	Electrical Test not required Magnification 50X	Well tinned ( <u>&gt;</u> 95% covered)
- Wetting		SMD conditions:	No visible damage
		1st step: method B, aging 4 hours at 155 °C dry heat	
		2nd step: leadfree solder bath at 245±3 °C	
		Dipping time: 3±0.5 seconds	
-Leaching	J-STD-002 test D	Leadfree solder ,260°C, 30 seconds	No visible damage
		immersion time	
-Resistance	MIL-STD 202 Method 210	Condition B, no pre-heat of samples	$\pm (0.5\% + 0.05\Omega)$ for 0.1%/
to Soldering Heat	IEC 60115-1 4.18	Leadfree solder, 260 °C ±5°C, 10 ±1 seconds	0.5%/ 1% tol.
		immersion time	$\pm (1\%+0.05\Omega)$ for 5% tol.
		Procedure 2 for SMD: devices fluxed and	<50m $\Omega$ for jumper
		cleaned with isopropanol	



# **REVISION HISTORY**

REVISION	DATE	CHANGE NOTIFICATION	DESCRIPTION
Version 0	2016-07-26		- First issue of this specification